Description
Thixotropic two-part epoxy adhesive. Its viscosity allows to be used for bonding, potting, filling and fairing applications.

Packaging: Kit 908g, Semkit® Injection cartridge 6oz/155g, dual cartridge 200ml and 50ml

Features
- Room temperature cure (≥ 18°C/64°F)
- Outstanding mechanical properties over a wide range of temperature (-55°C/-67°F to 180°C/356°F)
- Suitable for radome repair, non-metallic filler

Uncured Adhesive Properties

<table>
<thead>
<tr>
<th></th>
<th>Part A</th>
<th>Part B</th>
<th>Mixture</th>
</tr>
</thead>
<tbody>
<tr>
<td>Colour</td>
<td>Blue</td>
<td>Black</td>
<td>Grey</td>
</tr>
<tr>
<td>Brookfield viscosity at 23°C / 73°F (Poise)</td>
<td>4000 to 8000</td>
<td>100 to 700</td>
<td>1600</td>
</tr>
<tr>
<td>Density (g/m³)</td>
<td>1.4</td>
<td>1.0</td>
<td>1.3</td>
</tr>
<tr>
<td>Standard shelf-life (≤ 23°C / 73°F) from date of shipment</td>
<td>1 year</td>
<td>1 year</td>
<td></td>
</tr>
</tbody>
</table>

Instructions For Use
Refer to the Safety Data Sheet before handling.

- Mixing: Mix ratio by weight: Part A/Part B 100/30
  Thoroughly mix both parts until the resulting color is a consistent grey
  Pot-life of 100g mass (Part A + B) at 23°C/73°F ≈ 150 minutes.
  Do not mix quantities greater than 450g as dangerous heat build-up can occur
- Bonding surfaces should be clean, dry and properly prepared
- Curing: 3 to 5 days at 23°C/73°F to achieve optimal performance

The polymerisation time can be reduced by heating at maximum 93°C/200°F (leave product for at least 4h at room temperature before heating). For example, 1h at 65°C/149°F to obtain the best performance.
HexBond™ EA9395 STRUCTIL Epoxy Paste Adhesive

Bond Strength Performance After Cure

<table>
<thead>
<tr>
<th>Test Temperature (°C/°F)</th>
<th>Shear (1) : Lap Shear Strength (MPa / psi)</th>
<th>Peel (2) : Bell Peel Strength (N/25mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>-55 / -67</td>
<td>15 / 2150</td>
<td>-</td>
</tr>
<tr>
<td>23 / 73</td>
<td>25 / 3600</td>
<td>65</td>
</tr>
<tr>
<td>80 / 176</td>
<td>20 / 2900</td>
<td>-</td>
</tr>
<tr>
<td>120 / 248</td>
<td>15 / 2150</td>
<td>-</td>
</tr>
<tr>
<td>150 / 302</td>
<td>11 / 1600</td>
<td>-</td>
</tr>
</tbody>
</table>

(1) According to EN 2243-1, on aluminum 2024T3 clad treated with sulfo-chromic acid etch, cure 5 days 23°C/73°F
(2) According to EN 2243-2, on aluminum 2024T3 clad treated with sulfo-chromic acid etch, cure 5 days at 23°C/73°F

This information is provided for informal purposes only, without legal responsibility and does not constitute a specification. Users are expected to perform adequate verification and testing to ensure that materials meet required specification.

For more information
Hexcel is a leading worldwide supplier of composite materials to aerospace and industrial markets. Our comprehensive range includes:

- HexTow® carbon fibers
- HexForce® reinforcements
- HiMax™ multiaxial reinforcements
- HexPly® prepregs
- HexAM™ additive manufacturing
- HexMC® molding compounds
- HexFlow® RTM resins
- HexTool® tooling materials
- HexWeb® honeycombs
- HexBond™ adhesives
- Engineered core
- Acousti-Cap® sound attenuating honeycomb
- Engineered products
- Polyspeed™ laminates

For US quotes, orders and product information call toll-free 1-800-688-7734. For other worldwide sales office telephone numbers and a full address list, please go to:

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